

## Fixed 600kHz Step-UP Converter for White LEDs

#### **Features**

- Wide Input Voltage from 2.7V to 6V
- Fixed 600kHz Switching Frequency
- Reference Voltage: 0.2V
- PWM brightness control with wide frequency range of 5KHz to 100KHz
- Build-in Power MOSFET: 0.3W
- Over-Voltage Protection
- Under Voltage Lockout Protection
- · Over Temperature Protection
- <1mA Quiescent Current during Shutdown</p>
- TDFN2x2-6 Package
- Halogen and Lead Free Available (RoHS Compliant)

## **Applications**

- · White LED Display Backlighting
- · Cell Phone and Smart Phone
- PDA, PMP, MP3
- Digital Camera

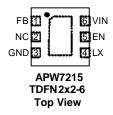
## **General Description**

The APW7215 is a current-mode and fixed frequency 600kHz boost converter with an integrated N-FET to drive white LEDs.

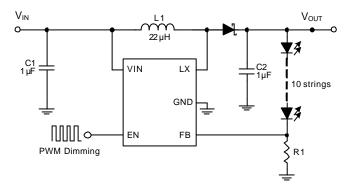
The series connection allows the LED current to be identical for uniform brightness. Its low on-resistance of NFET and low feedback voltage reduce power loss and achieve high efficiency. 600kHz Constant switching frequency allows using small-size inductor and both ofinput and output capacitors. An over voltage protection function, which monitors the output voltage via LX pin, stops switching of the IC if the LX voltage exceeds the over voltage threshold. An internal soft-start circuit eliminates the inrush current during start-up.

The APW7215 also integrates under-voltage lockout and over-temperature protection to protect the IC in abnormal conditions. The APW7215 is available in TDFN2x2-6 package.

## Pin Configuration



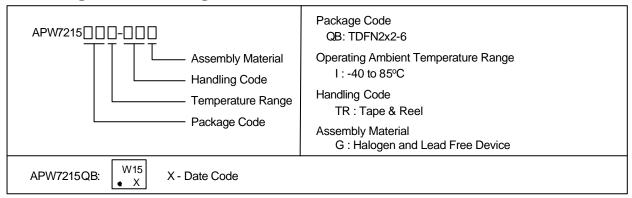
## **Simplified Application Circuit**



ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.



## **Ordering and Marking Information**



Note: ANPEC lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; w hich are fully compliant w ith RoHS. ANPEC lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. ANPEC defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by w eight in homogeneous material and total of Br and Cl does not exceed 1500ppm by w eight).

## Absolute Maximum Ratings (Note 1)

Symbol	Parameter	Rating	Unit
VN	VIN Pin to GND	-0.3 to 7	V
	FB and EN to GND	-0.3 ~ VIN	V
V <sub>L</sub> X	LX Pin to GND	-0.3 to 40	V
PD	Power Dissipation	Internally Limit	W
Тл	Maximum Junction Temperature	150	°C
Тѕтс	Storage Temperature Range	-65 to 150	°C
T <sub>SDR</sub>	Maximum Lead Soldering Temperature, 10 Seconds	260	°C

Note1: Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability

#### Thermal Characteristics

Symbol	Parameter	Typical Value	Unit	
$\theta_{JA}$	Junction-to-Ambient Resistance in free air (Note 2)	TDFN2x2-6	165	°C/W
θ <sub>JC</sub>	Junction-to-Case Resistance	TDFN2x2-6	20	°C/W

Note 2:  $\theta_{JA}$  is measured with the component mounted on a high effective thermal conductivity test board in free air.



# **Recommended Operating Conditions** (Note 3)

Symbol	Parameter	Range	Unit
VIN	VIN Input Voltage	2.7 ~ 6	V
Cin	Input Capacitor	1 ~	μF
Соит	Output Capacitor	1 ~	μF
L1	Converter Output Inductor	4.7 ~ 22	μН
TA	Ambient Temperature	-40 ~ 85	°C
Τı	Junction Temperature	-40 ~ 125	°C

Note 3: Please refer to the typical application circuit.

## **Electrical Characteristics**

Refer to the typical application circuits. These specifications apply over.  $V_{IN}$ =3.6V,  $T_A$ =25°C.

Symbol	Parameter	Test Conditions		APW7215		Unit	
Symbol	ratalileter rest conditions		Min.	Тур.	Max.	Oill	
SUPPLY	VOLTAGE AND CURRENT						
V <sub>IN</sub>	Input Voltage Range		2.7	-	6	V	
$I_{DD1}$		V <sub>FB</sub> = 0.4V, no switching	-	-	800	μА	
I <sub>DD2</sub>	Input DC Bias Current	V <sub>FB</sub> = GND, switching	-	1.2	1.7	mA	
I <sub>SD</sub>		EN = GND	-	-	1	μА	
UNDER-V	OLTAGE LOCKOUT						
	UVLO Threshold Voltage	V <sub>N</sub> Rising	1.9	2.2	2.4	V	
	UVLO Hysteresis Voltage	V <sub>N</sub> Falling	50	100	200	mV	
REFEREN	NCE AND OUTPUT VOLTAGES		-				
$V_{REF}$	Regulated Feedback Voltage	V <sub>N</sub> =2.7V ~ 6V	192	200	208	mV	
I <sub>FB</sub>	FB Input Current	V <sub>FB</sub> =1.23V	-1	-	1	μА	
INTERNA	L POWER SWITCH						
F <sub>sw</sub>	Switching Frequency		540	600	660	kHz	
Ron	Power Switch On Resistance	VIN=3.6V	-	0.3	0.7	Ω	
		VIN=3V	-	-	0.7	] Ω	
	LX Leakage Current	V <sub>EN</sub> =0V, V <sub>LX</sub> =35V, V <sub>IN</sub> = 6V	-	-	100	μА	
D <sub>MAX</sub>	LX Maximum Duty Cycle		92	95	-	%	
OUTPUT	OVER VOLTAGE PROTECTION		•	-	-		
$V_{LX\_OVP}$	Over Voltage Threshold	V <sub>LX</sub> Rising	36	38	40	V	
POWER S	SWITCH CURRENT LIMIT		·		-		
I <sub>LIM</sub>	N-Channel MOSFET Current Limit	Duty = D <sub>MAX</sub>	1.5	-	-	А	



# **Electrical Characteristics(Cont.)**

Refer to the typical application circuits. These specifications apply over.  $V_{IN}$ =3.6V,  $T_A$ =25°C.

Cumbal	Devenuetos	Test Conditions	APW7215			11!1
Symbol	Parameter Test Conditions —		Min.	Тур.	Max.	Unit
ENABLE	NABLE AND SHUTDOWN			•	•	
	Enable Voltage Threshold	V <sub>EN</sub> Rising	1	-	-	V
	Shutdown Voltage Threshold	V <sub>EN</sub> Falling	-	-	0.4	V
	EN Pulled Low Resistance		-	800	-	kΩ
	EN Dimming Minimum Enable Pulsed Width	Use V <sub>EN</sub> =3V to enable to device, PWM Dimming Frequency=5k to 100k Hz	4	-	-	%
OVER-TE	MPERATURE PROTECTION					
T <sub>OTP</sub>	Over-Temperature Protection <sup>(Note 4)</sup>	T」Rising	-	150	-	°C
	Over-Temperature Protection Hysteresis (Note 4)	T <sub>J</sub> Falling	-	40	-	°C

Note 4: Guaranteed by design, not production tested.

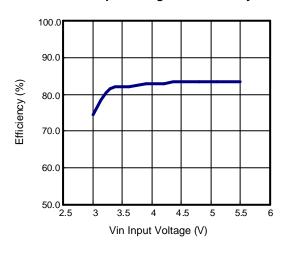
# **Pin Description**

PIN.		FUNCTION
TDFN-2x2-6	NAME	FUNCTION
1	FB	Feedback Pin. Connect this pin to cathode of the lowest LED and current-sense resistor (R1). Calculate resistor value according to R1=V <sub>REF</sub> /I <sub>LED</sub> .
2	NC	No Commend.
3	GND	Power and signal ground pin.
4	LX	Switch pin. Connect this pin to inductor/diode here.
5	EN	Enable Control Input. Forcing this pin above 1.0V enables the device, or forcing this pin below 0.4V to shut it down. In shutdown, all functions are disabled to decrease the supply current below 1µA.
6	VIN	Main Supply Pin. Must be closely decoupled to GND with a 1μF or greater ceramic capacitor.
Exposed Pad	GND	Connecting this pad to GND.

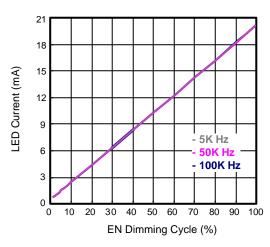


## **Typical Operating Characteristics**

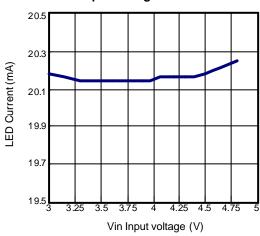
Vin Input Voltage vs. Efficiency



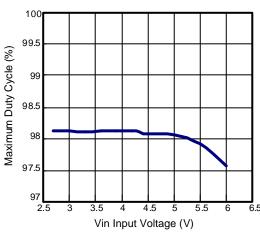
**EN Dimming Cycle vs. LED Current** 



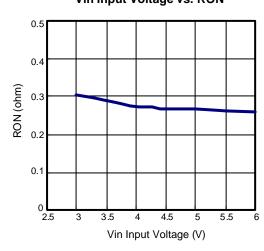
Vin Input Voltage vs. LED Current



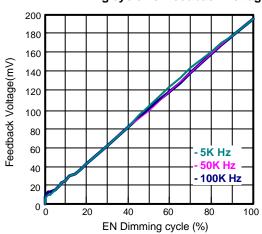
Vin Input Voltage vs. Max Duty Cycle



Vin Input Voltage vs. RON



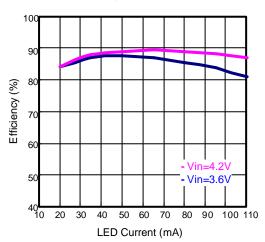
**EN Dimming cycle vs. Feedback Voltage** 





# **Typical Operating Characteristics**

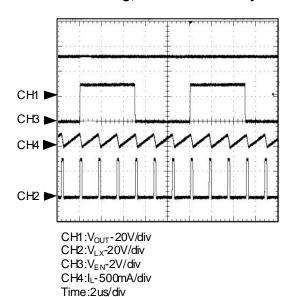
## Efficiency vs. LED Current



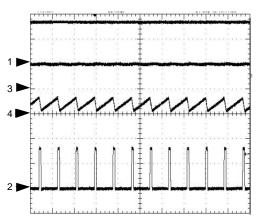


## **Operating Waveforms**

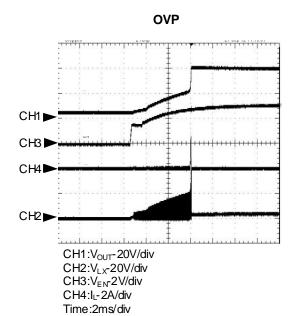
## Dimming, 100K Hz @50% duty

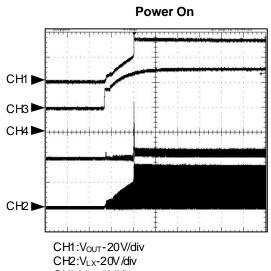


#### **Normal Operation**



CH1: $V_{OUT}$ -20V/div CH2:Lx-20V/div CH3: $V_{FB}$ -200 mV/div CH4: $I_L$ -500mA/div Time:2us/div



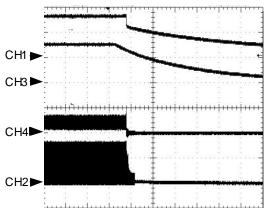


CH2:V<sub>LX</sub>-20V/div CH3:V<sub>EN</sub>-2V/div CH4:I<sub>L</sub>-1A/div Time:4ms/div



# **Operating Waveforms**

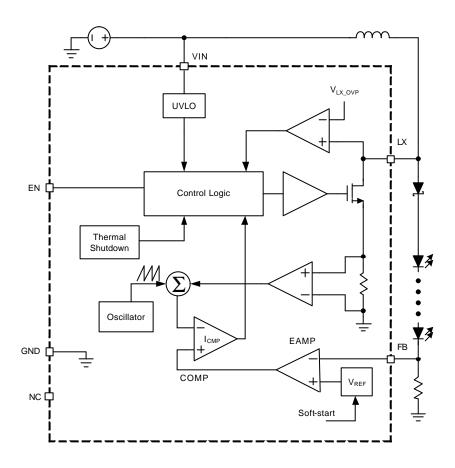




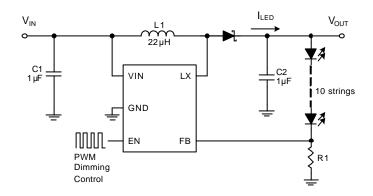
 $\begin{array}{l} CH1:V_{OUT}\text{-}20V/\text{div}\\ CH2:V_{LX}\text{-}20V/\text{div}\\ CH3:V_{EN}\text{-}2V/\text{div}\\ CH4:I_{L}\text{-}500\text{mA/div}\\ Time:200\text{ms/div} \end{array}$ 



# **Block Diagram**



# **Typical Application Circuits**





## **Function Description**

#### **Main Control Loop**

The APW7215 is a constant frequency current-mode switching regulator. During normal operation, the internal N-channel power MOSFET is turned on each cycle when the oscillator sets an internal RS latch and turned off when an internal comparator (ICMP) resets the latch. The peak inductor current at which ICMP resets the RS latch is controlled by the voltage on the internal COMP node, which is the output of the error amplifier (EAMP). An external current-sense resistor connected between cathode of the lowest LED and ground allows the EAMP to receive a current feedback voltage  $V_{\scriptscriptstyle FB}$  at FB pin. When the LEDs voltage decreases to cause the LEDs current to decrease, it causes a slightly decrease in V<sub>FR</sub> relative to the reference voltage, which in turn causes the internal COMP voltage to increase until the LEDs current reaches the set point.

#### VIN Under-Voltage Lockout (UVLO)

The Under-Voltage Lockout (UVLO) circuit compares the input voltage at VIN with the UVLO threshold (2.2V rising, typical) to ensure the input voltage is high enough for reliable operation. The 100mV (typ) hysteresis prevents supply transients from causing a restart. Once the input voltage exceeds the UVLO rising threshold, startup begins. When the input voltage falls below the UVLO falling threshold, the controller turns off the converter.

#### Soft-Start

The APW7215 has a built-in soft-start to control the N channel MOSFET current raises during start-up. During soft-start, an internal ramp voltage connected to one of the inverting inputs of the current limit comparator. The inductor current limit is proportional to the voltage. When the threshold voltage of the internal soft-start comparator is reached, the full current limit is released.

#### **Current-Limit Protection**

The APW7215 monitors the inductor current flowing through the N-channel MOSFET, and limits the current peak at current-limit level to prevent loads and the device from damages in overload conditions.

#### **Over-Temperature Protection (OTP)**

The over-temperature circuit limits the junction temperature of the APW7215. When the junction temperature exceeds  $150^{\circ}$ C, a thermal sensor turns off the power MOSFET, allowing the device to cool. The thermal sensor allows the converter to start a soft-start process and regulate the LEDs current again after the junction temperature cools by  $40^{\circ}$ C. The OTP is designed with a  $40^{\circ}$ C hysteresis to lower the average Junction Temperature (T<sub>J</sub>) during continuous thermal overload conditions, increasing the lifetime of the device.

#### Enable/Shutdown

Driving EN to ground places the APW7215 in shutdown mode. When in shutdown, the internal power MOSFET turns off, all internal circuitry shuts down and the quiescent supply current reduces to  $1\mu A$  maximum. This pin also could be used as a digital input allowing brightness controlled by using a PWM signal with frequency from 5kHz to 100kHz. The 0% duty cycle of PWM signal corresponds to zero LEDs current and 100% corresponds to full one. If use EN Pin to enable the device, suggestion dimmim g duty range is from 15% to 100% at 100kHz dimmimg frequency.

#### **Open-LED Protection**

In driving LED applications, the feedback voltage on FB pin falls down if one of the LEDs, in series, is failed. Meanwhile, the converter unceasingly boosts the output voltage like an open-loop operation. Therefore, an over-voltage protection monitoring the output voltage via LX pin prevents the LX and the output voltages from exceeding their maximum voltage ratings. Once the voltage on the LX pin rises above the OVP threshold, the converter stops switching and prevents the output voltage from rising. The converter can work again when the LX voltage falls below the falling of OVP voltage threshold.



## **Application Information**

#### **Input Capacitor Selection**

The input capacitor ( $C_{\rm IN}$ ) reduces the ripple of the input current drawn from the input supply and reduces noise injection into the IC. The reflected ripple voltage will be smaller when an input capacitor with larger capacitance is used. For reliable operation, it is recommended to select the capacitor with maximum voltage rating at least 1.2 times of the maximum input voltage. The capacitors should be placed close to the VIN and the GND.

#### **Inductor Selection**

Selecting an inductor with low dc resistance reduces conduction losses and achieves high efficiency. The efficiency is moderated whilst using small chip inductor which operates with higher inductor core losses. Therefore, it is necess ary to take further consideration while choosing an adequate inductor. Mainly, the inductor value determines the inductor ripple current: larger inductor value results in smaller inductor ripple current and lower conduction losses of the converter. However, larger inductor value generates slower load transient response. A reasonable design rule is to set the ripple current,  $\Delta I_L$ , to be 30% to 50% of the maximum average inductor current,  $I_{L(AVG)}$ . The inductor value can be obtained as below,

$$L \ge \left(\frac{V_{IN}}{V_{OUT}}\right)^{2} \times \frac{V_{OUT} - V_{IN}}{F_{SW} \cdot I_{OUT(MAX)}} \times \frac{\eta}{\left(\frac{\Delta I_{L}}{I_{L(AVG)}}\right)}$$

where

 $V_{IN}$  = input voltage

 $V_{OUT}$  = output voltage

 $F_{sw}$  = switching frequency in MHz

 $I_{OUT} = maximum output current in amp.$ 

= Efficiency

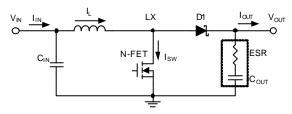
 $\Delta I_L / I_{L(AVG)} = inductor ripple current/average current (0.3 to 0.5 typical)$ 

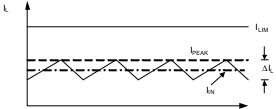
To avoid the saturation of the inductor, the inductor should be rated at least for the maximum input current of the converter plus the inductor ripple current. The maximum input current is calculated as below:

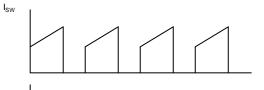
$$I_{IN(MAX)} = \frac{I_{OUT(MAX)} \cdot V_{OUT}}{V_{IN} \cdot \eta}$$

The peak inductor current is calculated as the following equation:

$$I_{PEAK} = I_{IN(MAX)} + \frac{1}{2} \cdot \frac{V_{IN} \cdot \left(V_{OUT} - V_{IN}\right)}{V_{OUT} \cdot L \cdot F_{SW}}$$









#### **Output Capacitor Selection**

The current-mode control scheme of the APW7215 allows the usage of tiny ceramic capacitors. The higher capacitor value provides good load transients response. Ceramic capacitors with low ESR values have the lowest output voltage ripple and are recommended. If required, tantalum capacitors maybe used as well. The output ripple is the sum of the voltages across the ESR and the ideal output capacitor.

$$\begin{split} &V_{\text{OUT}} = &V_{\text{ESR}} + &V_{\text{COUT}} \\ &\Delta V_{\text{COUT}} \approx \frac{I_{\text{OUT}}}{C_{\text{OUT}}} \cdot \left( \frac{V_{\text{OUT}} - V_{\text{IN}}}{V_{\text{OUT}} \cdot F_{\text{SW}}} \right) \end{split}$$

$$\Delta V_{ESR} \approx I_{PEAK} \cdot R_{ESR}$$

where  $I_{PEAK}$  is the peak inductor current.



## Application Information (Cont.)

#### **Output Capacitor Selection (Cont.)**

For ceramic capacitor application, the output voltage ripple is dominated by the  $\Delta V_{\text{COUT}}$ . When choosing the input and output ceramic capacitors, the X5R or X7R with their good temperature and voltage characteristics are recommended.

#### **Output Voltage Setting**

In figure 1, the converter regulates the voltage on FB pin, connected with the cathode of the lowest LED and the current- sense resistor R1 at  $V_{REF}$ . Therefore, the current ( $I_{LED}$ ), flowing via the LEDs and the R1, is calculated by the following equation:

$$I_{LED} = \frac{V_{REF}}{R1}$$

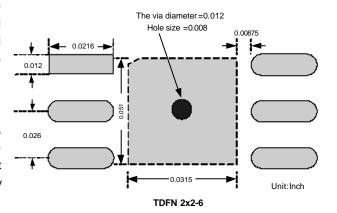
#### **Layout Consideration**

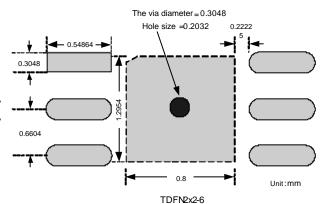
For all switching power supplies, the layout is an important step in the design especially at high peak currents and switching frequencies. If the layout is not carefully done, the regulator might show noise problems and duty cycle litter.

- The input capacitor should be placed close to the VIN and the GND without any via holes for good input voltage filtering.
- To minimize copper trace connections that can inject noise into the system, the inductor should be placed as close as possible to the LX pin to minimize the noise coupling into other circuits.
- 3. Since the feedback pin and network is a high impedance circuit the feedback networks hould be routed away from the inductor. The feedback pin and feedback network should be shielded with a ground plane or trace to minimize noise coupling into this circuit.
- 4. A star ground connection or ground plane minimizes ground shifts and noise is recommended.

#### **Recommended Minimum Footprint**

layout

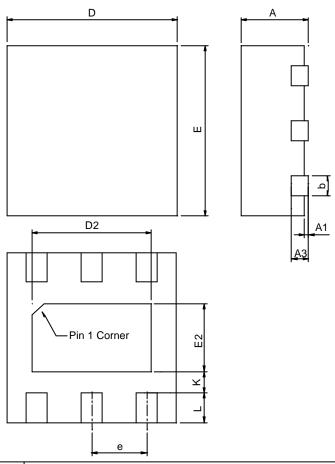






# **Package Information**

### TDFN2x2-6

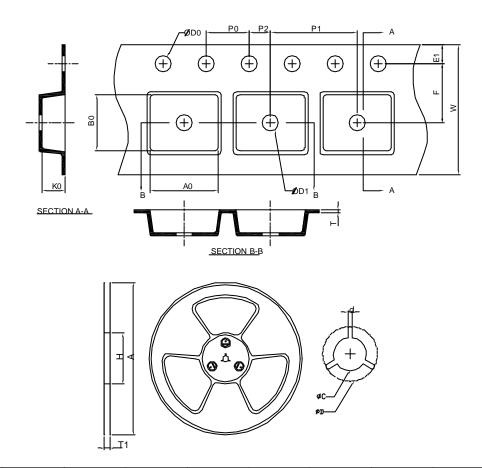


Ş		TDFN	2x2-6	
S≻ <b>∑</b> BOL	MILLIM	ETERS	INC	HES
2	MIN.	MAX.	MIN.	MAX.
Α	0.70	0.80	0.028	0.031
A1	0.00	0.05	0.000	0.002
АЗ	0.20	REF	0.008 REF	
b	0.18	0.30	0.007	0.012
D	1.90	2.10	0.075	0.083
D2	1.00	1.60	0.039	0.063
Е	1.90	2.10	0.075	0.083
E2	0.60	1.00	0.024	0.039
е	0.65 BSC		0.026	6 BSC
L	0.30	0.45	0.012	0.018
K	0.20		0.008	

Note: 1. Followed from JEDEC MO-229 WCCC.



# **Carrier Tape & Reel Dimensions**



Application	Α	Н	T1	С	d	D	W	E1	F
	330.0	50 MIN.	12.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	12.0 <b>±</b> 0.30	1.75 <b>±</b> 0.10	5.5 <b>±</b> 0.05
TDFN2x2-6	P0	P1	P2	D0	D1	Т	A0	В0	K0
	4.0 ±0.10	8.0 <b>±</b> 0.10	2.0 ±0.05	1.5+0.10 -0.00	1.5 MIN.	0.6+0.00 -0.40	2.35±0.20	2.35±0.20	1.30 <b>±</b> 0.20

(mm)

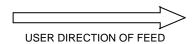
## **Devices Per Unit**

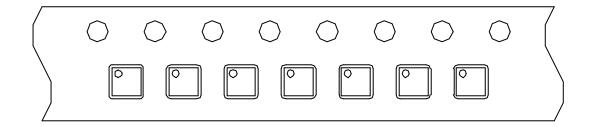
Package Type	Unit	Quantity
TDFN2x2-6	Tape & Reel	3000



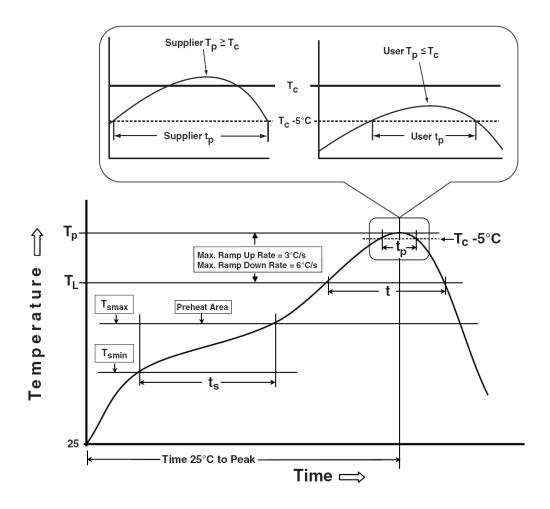
# **Taping Direction Information**

### TDFN2x2-6





## **Classification Profile**





## **Classification Reflow Profiles**

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly				
Preheat & Soak Temperature min (T <sub>smin</sub> ) Temperature max (T <sub>smax</sub> ) Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-120 seconds				
Average ramp-up rate (T <sub>smax</sub> to T <sub>P</sub> )	3 °C/second max.	3°C/second max.				
Liquidous temperature (TL) Time at liquidous (tL)	183 °C 60-150 seconds	217 °C 60-150 seconds				
Peak package body Temperature (T₂)*	See Classification Temp in table 1	See Classification Temp in table 2				
Time (t <sub>P</sub> )** within 5°C of the specified classification temperature (T <sub>c</sub> )	20** seconds	30** seconds				
Average ramp-down rate (Tp to Tsmax)	6 °C/second max.	6 °C/second max.				
Time 25°C to peak temperature	6 minutes max.	8 minutes max.				
* Tolerance for peak profile Temperature (T <sub>P</sub> ) is defined as a supplier minimum and a user maximum.						

Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

Package	Volume mm <sup>3</sup>	Volume mm <sup>3</sup>
Thickness	<350	³350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

# **Reliability Test Program**

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HOLT	JESD-22, A108	1000 Hrs, Bias @ T⊨125°C
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
тст	JESD-22, A104	500 Cycles, -65°C~150°C
НВМ	MIL-STD-883-3015.7	VHBM 2KV
MM	JESD-22, A115	VMM 200V
Latch-Up	JESD 78	10ms, 1 <sub>tr</sub> 100mA

<sup>\*\*</sup> Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.



### **Customer Service**

### **Anpec Electronics Corp.**

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